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SECTION II—CLAIMS

1. (Currently Amended) A method, comprising:

~~removably optically coupling a test structure to a device on a wafer, the test structure included on the wafer and, comprising a first region, a second region and an interface defined between the first and second regions, the second region comprising a material different from a material of the first region, wherein the test structure is optically coupled to the device in a manner to allow the interface to direct a light beam emitted from the device in a direction different from an original direction of the emitted light beam; and~~

forming a light-emitting device on a wafer, wherein the device emits light substantially parallel to the plane of the wafer through one or both of a front facet and a back facet;

removably optically coupling a test structure to one or both of the front facet and the back facet, the test structure ^{formed on the wafer and} comprising a first region, a second region, and an interface defined between the first and second regions, the second region comprising a material different from a material of the first region, wherein the interface can direct the light beam emitted from the front facet or the back facet in a direction different from an original direction of the emitted light beam; and

detecting the light beam directed from the interface.

2. (Currently Amended) The method of claim 1 wherein optically coupling the test structure to the one or both of the front facet and the back facet a device includes optically coupling the test structure to a side-emitting laser.

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3. (Original) The method of claim 1 wherein directing the light beam comprises reflecting the light beam from the interface defined between the first and the second regions and wherein the first and the second regions are comprised of materials having two different refractive indexes.
4. (Canceled)
5. (Currently Amended) The method of claim 1 wherein the a light detector is positioned to receive the light beam directed from the interface.
6. (Original) The method of claim 1 wherein detecting the light beam includes detecting a frequency and intensity of the emitted light beam.
7. (Original) The method of claim 1 wherein the detecting the light beam includes detecting the light beam with at least one of a photodiode, avalanche photodiode, positive-intrinsic-negative (PIN) detector, and a charge coupled device.
8. (Original) The method of claim 7 wherein a light detector is integrated into the test structure.
9. -18. (Canceled)

Canceled 19. ~~(Withdrawn)~~ A process, comprising:

forming a semiconductor device on a wafer, and

forming a test structure on the wafer, the test structure optically coupled to an end of the semiconductor device, comprising:

depositing a photoresist material on a first region adjacent to the semiconductor device;

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selectively removing portions of the photoresist material to form inclined sections separated by openings to expose the first region; and

selectively etching the first region through the openings to remove portions of the first region to form an incline on the first region based on the incline of the sections and to form a second region.

Canceled 20. (Withdrawn) The process of claim 19, further comprising depositing a reflective material on the incline of the first region.

Canceled 21. (Withdrawn) The process of claim 19 wherein the first region has a first index of refraction, the process further comprising placing a material with a second index of refraction over the first region to fill the second region.

Canceled 22. (Withdrawn) The process of claim 19, further comprising forming a photosensitive device adjacent to the end of the semiconductor device.

23.-26. (Canceled)

27. (Currently Amended) A method, comprising:

emitting a light beam from a front facet or a back facet of a device formed on a wafer, the light beam being emitted in a direction substantially parallel to the plane of the wafer;

directing ~~[[a]] the light beam emitted from a device in a wafer~~ in a direction different from an original direction ~~of the light beam as emitted from the device;~~ via use of a test structure included on the wafer and removably optically coupled to the front facet or back facet of the device;

detecting the directed light beam; and

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evaluating the detected light beam.

28. (Original) The method of claim 27 wherein directing the light beam comprises redirecting the emitted light beam from an interface between two materials of different indexes of refraction.
29. (Original) The method of claim 27 wherein evaluating the detected light beam comprises evaluating at least one of an intensity of the detected light beam and a frequency of the detected light beam.